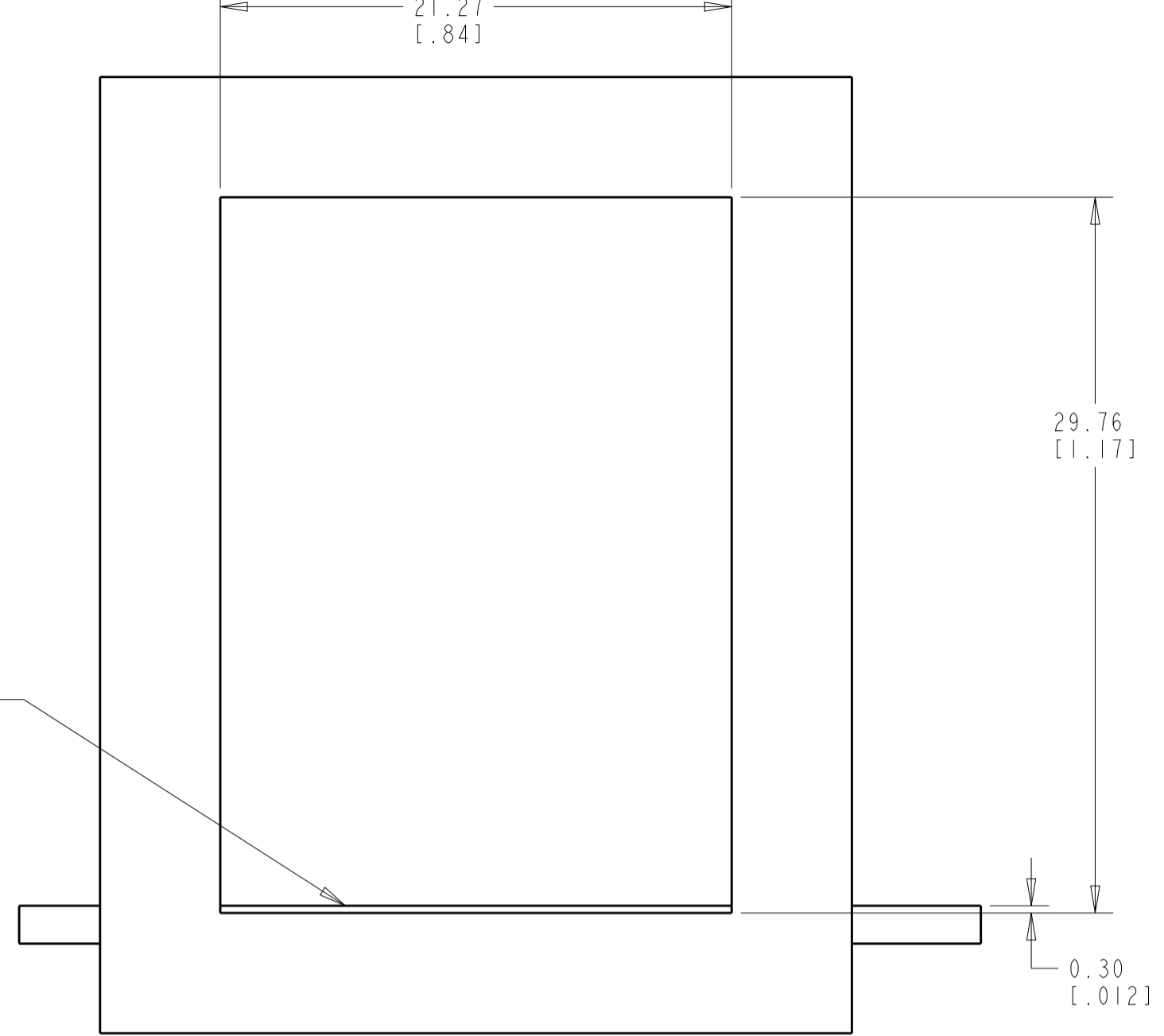
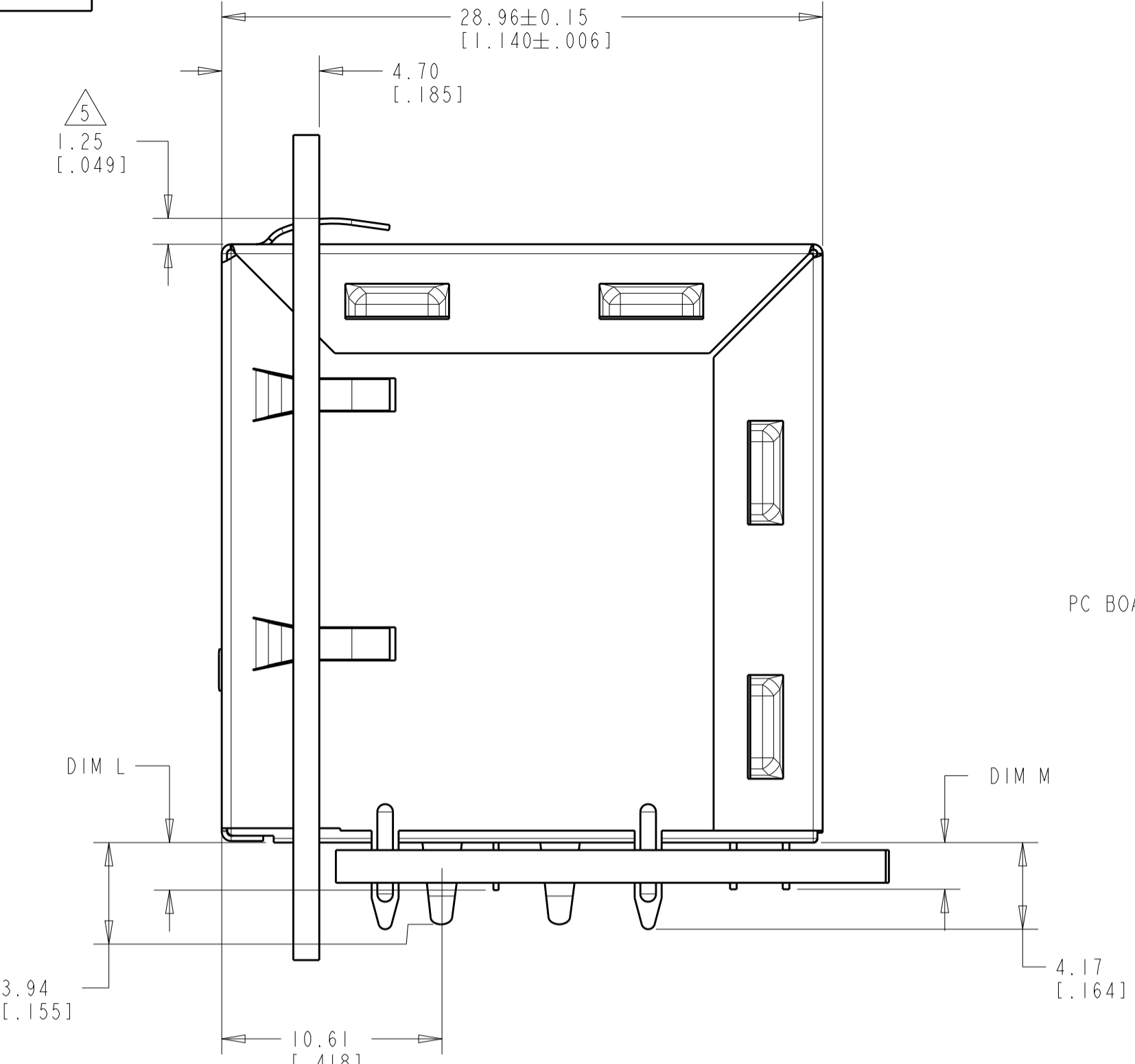
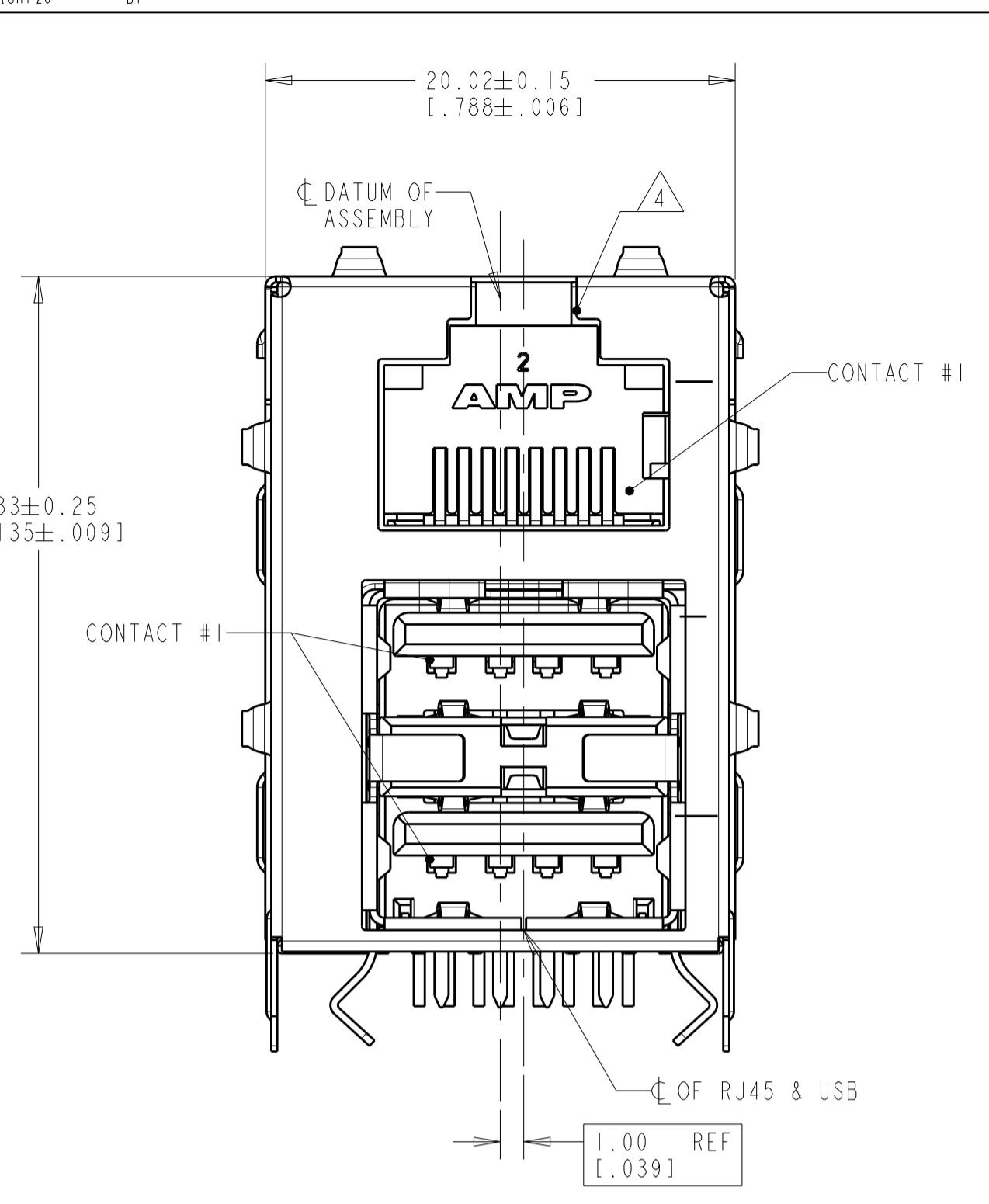


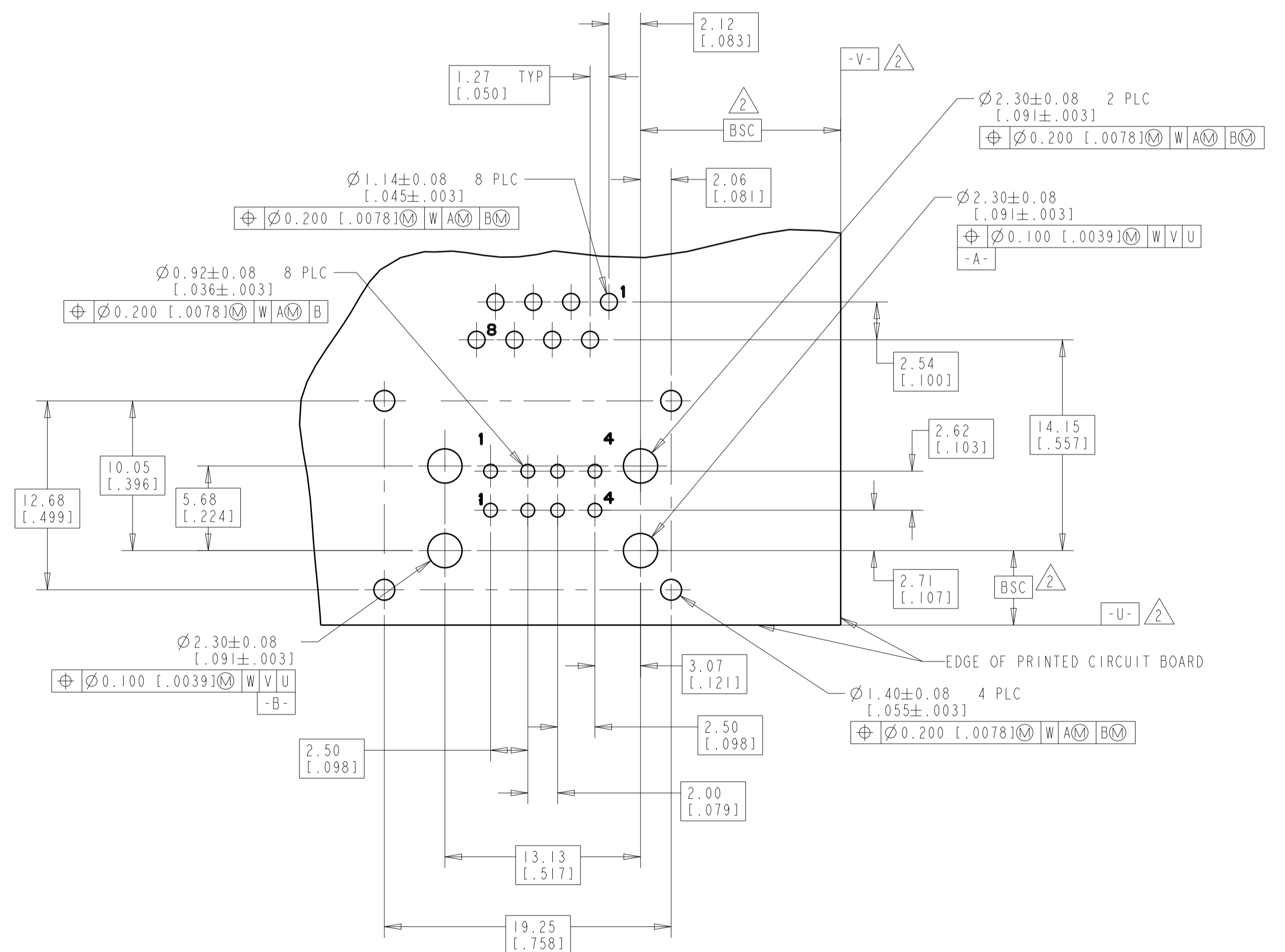
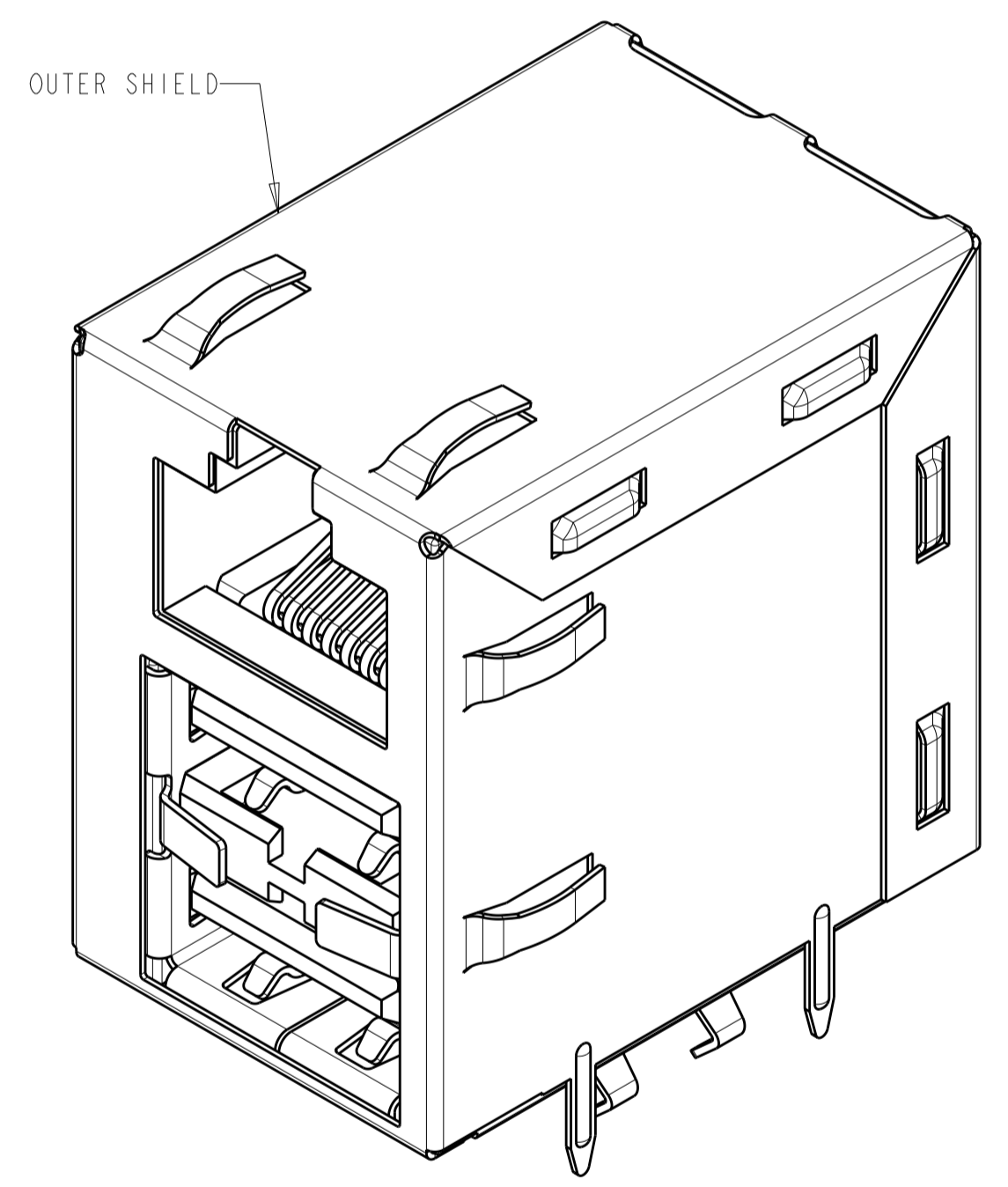
REVISIONS				
P.	LTN.	DESCRIPTION	DATE	APP'D.
D		REVISED PER ECO-16-016643	17NOV2016	LL SH
E		ECO-16-018208	19DEC2016	LL SH



PANEL CUTOUT

PANEL CUTOUT SHOWN IN VIEW FOR DIMENSIONAL LOCATION

1. MATERIAL:
- HOUSING: PLASTIC HOUSINGS: UL94V-0/5V THERMOPLASTIC, COLOR: BLACK
 TERMINAL: USB: 0.251±0.013 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm NICKEL. IN LOCALIZED GOLD PLATE AREA 0.076µm MIN GOLD OVER 0.76µm MIN PALLADIUM-NICKEL IS ADDED OVER NICKEL UNDERPLATE. IN SOLDER AREA 3.8µm MIN TIN IS ADDED OVER NICKEL UNDERPLATE.
 RJ45: 0.318 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm MIN THICK NICKEL. IN LOCALIZED GOLD PLATE AREA 1.27µm MIN THICK GOLD IS ADDED OVER NICKEL UNDERPLATE. IN SOLDER AREA 3.8µm MIN TIN IS ADDED OVER NICKEL UNDERPLATE.
 SHIELD: OUTER: 0.254 THICK COPPER-ZINC ALLOY PREPLATED WITH TIN 2µm TO 3.8µm THICK.
 INNER: 0.318 THICK COPPER-ZINC ALLOY PREPLATED WITH TIN 2µm TO 3.8µm THICK.
 USB: 0.318 THICK PHOSPHOR-BRONZE PREPLATED WITH 5.1µm MIN TIN
- 2 DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER
 - 3 RECOMMENDED PC BOARD THICKNESS OF 1.57 [0.062] FOR 1888371-1, RECOMMENDED PC BOARD THICKNESS OF 2.38 [0.093] FOR 1888371-2.
 - 4 RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F
 - 5 BEFORE INSERTION IN PANEL CUTOUT



RECOMMENDED PCB LAYOUT

2.85 ± 0.25 [0.112 ± 0.009]	2.85 ± 0.25 [0.112 ± 0.009]	1888371-2
2.29 ± 0.25 [0.090 ± 0.009]	2.25 ± 0.25 [0.089 ± 0.009]	1888371-1
DIM L	DIM M	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC	±
1 PLC	±0.131 [0.005]
2 PLC	±
3 PLC	±
4 PLC	±
ANGLES	±1°

MATERIAL: SEE NOTE 1

FINISH: SEE NOTE 1

DATE: 16FEB2006

BY: H/L.A.MAYER

CHK: J.WESTMAN

APP'D: S.FLICKINGER

NAME: ASSEMBLY, RJ-45 MODULAR JACK OVER STACKED USB RECEPTACLE

SIZE: A1

CAGE CODE: 00779

DRAWING NO: 1888371

RESTRICTED TO: -

CUSTOMER DRAWING

SCALE: 4:1

SHEET: 1 OF 1

REV: E